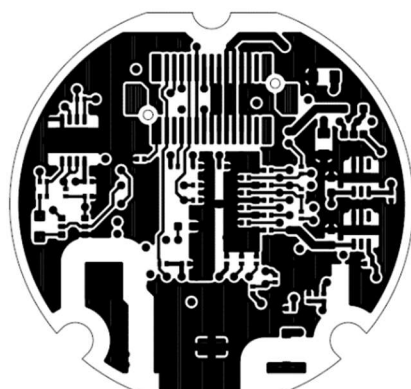
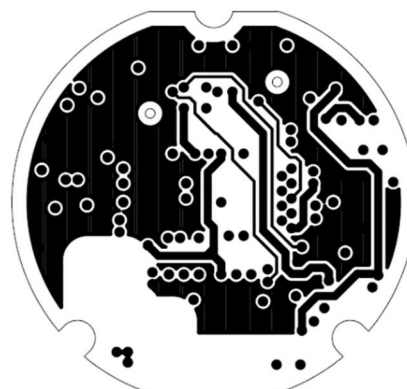


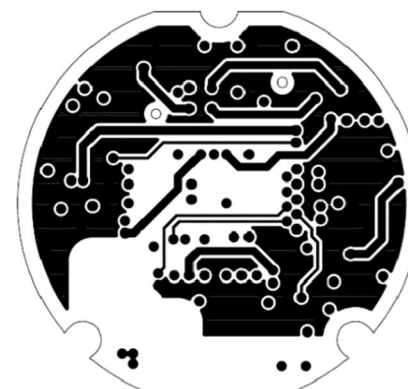
SILK PRINT FOR
PARTS SIDE



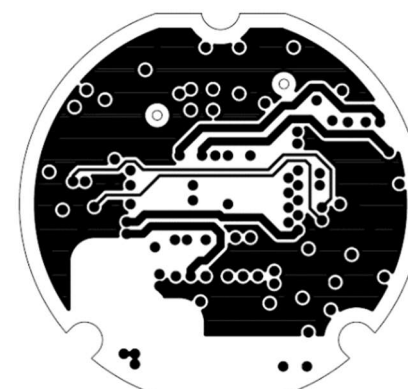
PARTS SIDE



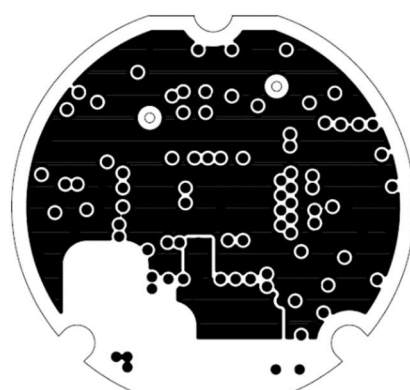
INNER LAYER
(2 LAYER)



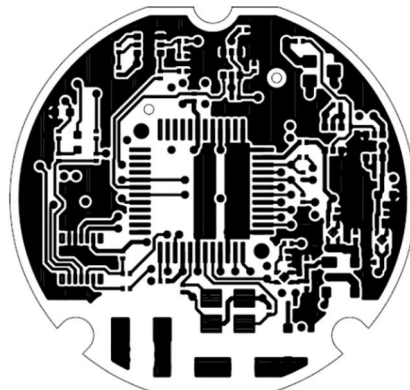
INNER LAYER
(3 LAYER)



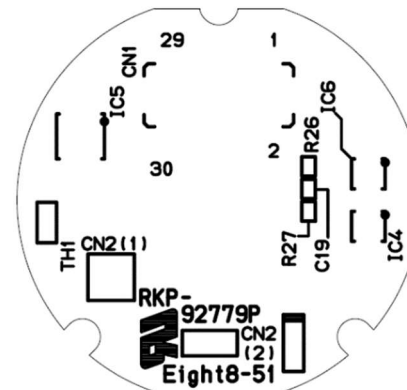
INNER LAYER
(4 LAYER)



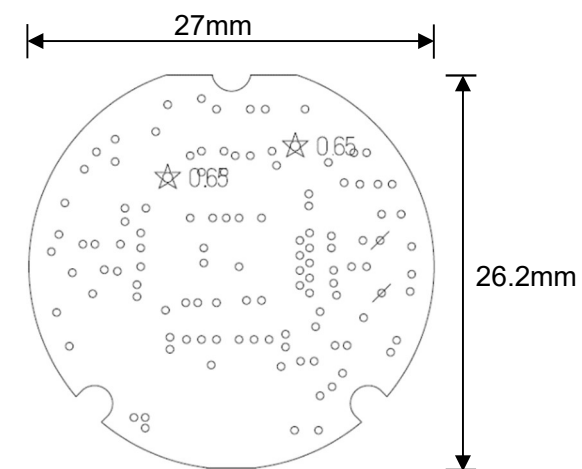
INNER LAYER
(5 LAYER)



SOLDERING SIDE



SILK PRINT FOR
SOLDERING SIDE



THROUGH HOLE

MARK	DIAGRAM	HOLE
○	φ0.25	TH
/	φ0.25	TH
☆0.65	φ0.65	NTH

All drawings are view of parts side

SCALE 2:1

SPECIFICATION FOR PCB

- PCB No. : RKP-92779P
- Material : Glass epoxy
- Thickness : 1.2mm
- Layer number : 6
- Thickness copper film
Surface : 35um, Inner : 35um
- Copper thickness of the via's : 35um above.
- Minimum conductor width : 0.15mm
- CTI : 100 above.

注 記 NOTES		改版担当者 REV. BY	改版日 REVISED	名 称 NAME DIGITAL PCB FOR MODEL ESF
改版回数 REV.	0	総頁数 PAGES	1	
承認 APPROVED	検 討 CHECKED	製 図 DRAWN	作成日 DATE	図 番 DWG. NO.
北村正英	小野圭	秋山友	2020. 10. 15	E 3 - 6 9 9 1 - 6 1 3 8 - 5 0 - 0 1 A